Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3443564	(die chip ic (integrated adj circuit) semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:37
L2	52782	(bonding bond) with (pattern wiring trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:37
L3	38	1 same 2 same (rearrange rearrangement rearranging)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:47
L4	431	1 and 2 and (rearrange rearrangement rearranging)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:47
L5	242	4 and (package packaging packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:48
L6	214	5 not 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/23 16:48